Elastic-Plastic and Fully Plastic Fatigue Crack Growth

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The objective of the elastic-plastic and fully plastic fatigue crack growth research effort is to develop methods and computer programs for analytically predicting lifetimes of flawed metallic structures that experience appreciable plastic cracktip stresses. In order to reach this objective, existing elastic-plastic stress intensity (*J*-integral) solutions from the Electric Power Research Institute have been collected and combined with new analytical solutions developed from finite element solutions with the reference stress method. The list of available J-integral solutions is the most extensive ever collected. An overview of the solutions is as follows:

J-integral solutions for primary loads based on Electric Power Research Institute solutions and the reference stress method:

- Two-dimensional axial flaws in pressurized cylinders
- Two-dimensional circumferential flaws in cylinders, axial end force
- Two-dimensional crack from a hole in biaxial stress field
- Two-dimensional single-edge cracked plate (plane stress and plane strain)
- Two-dimensional center-cracked plate (plane stress and plane strain)
- Through wall circumferential crack, axial end force

• Through wall circumferential crack, bending moment.

J-integral solutions for primary loads based on newly developed finite element solutions and the reference stress method:

- Three-dimensional surface flaw in a finite width plate subjected to a tensile end force (two degrees of freedom—near surface and deepest point)
- Three-dimensional corner flaw in a finite width plate subjected to a tensile end force (two degrees of freedom—near surface points).

Existing linear-elastic stress intensity solutions from the NASA/FLAGRO software have been combined with limit-load solutions and cyclic stress-strain curves to provide estimates for the *J* solutions with the reference stress method. A listing of these FLAGRO geometries includes:

- TC01: through center crack subjected to tension
- TC02: through edge crack subjected to tension or bending
- TC03: through crack from an offset hole in a plate
- TC04: through crack from hole in lug
- TC05: through crack from hole in a plate with a row of holes subjected to tension or bending
- TC06: through crack in a sphere
- TC07: axial through crack in a cylinder
- TC08: circumferential through crack in a cylinder subjected to tension or bending

- TC10: circumferential through crack from a hole in a cylinder
- EC01: embedded elliptical crack subjected to tension
- CC01: corner crack in a rectangular plate subjected to tension or through wall bending
- CC02: corner crack from a hole in a plate subjected to a bending moment
- CC03: corner crack from a hole in a lug
- SC01: surface crack in a rectangular plate subjected to tension or bending
- SC03: surface crack in a spherical pressure vessel
- SC04: longitudinal surface crack in a hollow cylinder
- SC05: thumbnail crack in a hollow cylinder subjected to tension or bending
- SC07: thumbnail crack in a solid cylinder subjected to tension or bending
- SC08: thumbnail crack in a thread root in a cylinder subjected to tension or bending
- SC09: circumferential crack at a thread root in a cylinder subjected to tension or bending.

In addition to *J*-integral solutions, crack-growth algorithms have been developed for some of the flaw geometries. The associated algorithm topics include:

Technology Programs

- Monotonic loading
- Cyclic loading
- Primary and secondary loading (mechanical and thermal)
- Combined primary loading (tension and bending)
- · Crack failure
- Crack closure
- Ductile tearing
- Materials data base.

Current plans are to incorporate these solutions into the NASA/FLAGRO software in order to allow free access to interested industries and other government agencies. A preliminary list of prioritized solutions to be coded into FLAGRO will include TC01, EC01, CC01, and SC01. These solutions will have a portion of the capabilities from each crack growth algorithm currently available.

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